

PRODUCT CHANGE NOTIFICATION

Ref Nr: **EBR-0176-2026062501**

Date: **Jun 25, 2026**

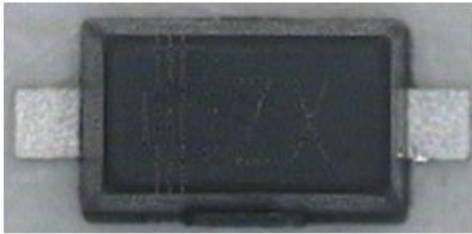
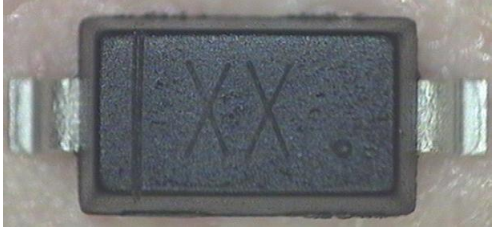
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TO: Customers who may concern

FROM: Product Marketing, CPC

HEREWITH YOU ARE INFORMED OF OUR INTENTION TO ADD A NEW DIODE ASSEMBLY LINE
DESCRIPTION:

To ensure supply chain security and expand supply capacity, we will add a new assembly line for Diode BAV116W effective Aug 30, 2026. Products from the new line are fully compatible with existing versions. Only appearance will change; all other characteristics comply with current specifications, including dimensions, electrical parameters (leakage current, breakdown voltage, etc.). Please refer to the comparison table below.

Before change	After change
	
	
	

REASONS: To ensure supply chain security for Diode BAV116W and expand supply capacity.

EXPECTED INFLUENCE ON PERFORMANCE: None

EXPECTED INFLUENCE ON QUALITY AND RELIABILITY: None

CHANGE:
Quality REPORTS available: Available based on customers' request

SAMPLES available: Any sample request please kindly contact with our sales

Implementation date: **Aug 30, 2026**
Type identification after change: Lot number

SUGGESTION FOR ALTERNATIVE PRODUCTS: None

Quality Manager:**Signature:****Date:**2026.07.31**Product Manager:****Signature:****Date:**2026.07.31**Sales Manager:****Signature:****Date:**2026.07.31

FOR MORE INFORMATION, CONTACT: YAGEO sales contact window

RETURN YOUR COMMENTS BEFORE: Aug 15, 2026

Remarks:

If customer has no feedback about this change before the customer response date, the change will be regarded as approved by customer automatically.

Comments:

Date:

Function:

Signature:

TECHNICAL CLARIFICATION STATEMENT

To enhance product reliability, improve compatibility with automated manufacturing, optimize performance, and ensure supply chain stability, we plan to change the lead form of the fast switching diode **BAV116W** from **flat lead** to **gull-wing lead**.

The justification for this change is as follows:

1. Improved Soldering Reliability

The gull-wing lead provides a larger contact area with the PCB pads, allowing better solder wetting. This helps reduce issues such as cold solder joints and misalignment, enhances joint strength, and lowers the risk of manufacturing defects.

2. Compatibility with Automated Production

The gull-wing lead is an industry-standard configuration and is fully compatible with existing high-speed SMT placement and reflow processes. No equipment modification is required, resulting in improved production efficiency and yield.

3. Enhanced Performance Stability

The improved lead-to-pad contact reduces thermal resistance and enhances heat dissipation, helping to lower junction temperature. In addition, reduced parasitic inductance supports stable switching

performance and signal integrity, particularly in high-frequency applications.

4. **Supply Chain Stability**

The gull-wing lead is a standard, widely available configuration with stable supply, shorter lead times, and more competitive cost. This change helps avoid the limitations and higher costs associated with customized flat lead designs, improving overall supply reliability.

Conclusion

This change does not affect the electrical characteristics, functionality, or PCB compatibility of the product. It is expected to systematically improve soldering reliability, production yield, and product standardization, providing customers with a more robust and higher-quality solution.

This change complies with industry standards and is considered both necessary and beneficial.

If samples or technical support are required, please feel free to contact us.

We kindly ask you to communicate this PCN to your end customers in a timely manner and evaluate demand in advance so that we can arrange production and supply accordingly.

Thank you for your understanding and support.